

1 Scope

The present specifications shall apply to an FMEN-2308.

2 Outline

Type	Silicon Schottky Barrier Diode
Structure	Resin Molded
Applications	High Frequency Rectification

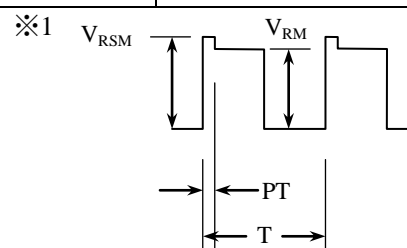
3 Flammability

UL94V-0(Equivalent)

4 Absolute maximum ratings

No.	Item	Symbol	Unit	Rating	Conditions
1	Transient Peak Reverse Voltage	V_{RSM}	V	85	PT \leq 500 ns Duty \leq 1/40 *1
2	Peak Reverse Voltage	V_{RM}	V	80	
3	Average Forward Current	$I_{F(AV)}$	A	30	Refer to derating curve in Section 7
4	Peak Surge Forward Current	I_{FSM}	A	150	10 ms. Half sine wave, one shot
5	I^2t Limiting Value	I^2t	A^2s	112.5	1 ms \leq t \leq 10 ms
6	Junction Temperature	T_j	$^{\circ}C$	-40 to +150	
7	Storage Temperature	T_{sig}	$^{\circ}C$	-40 to +150	

No.1,2,4&5 show ratings per one chip.

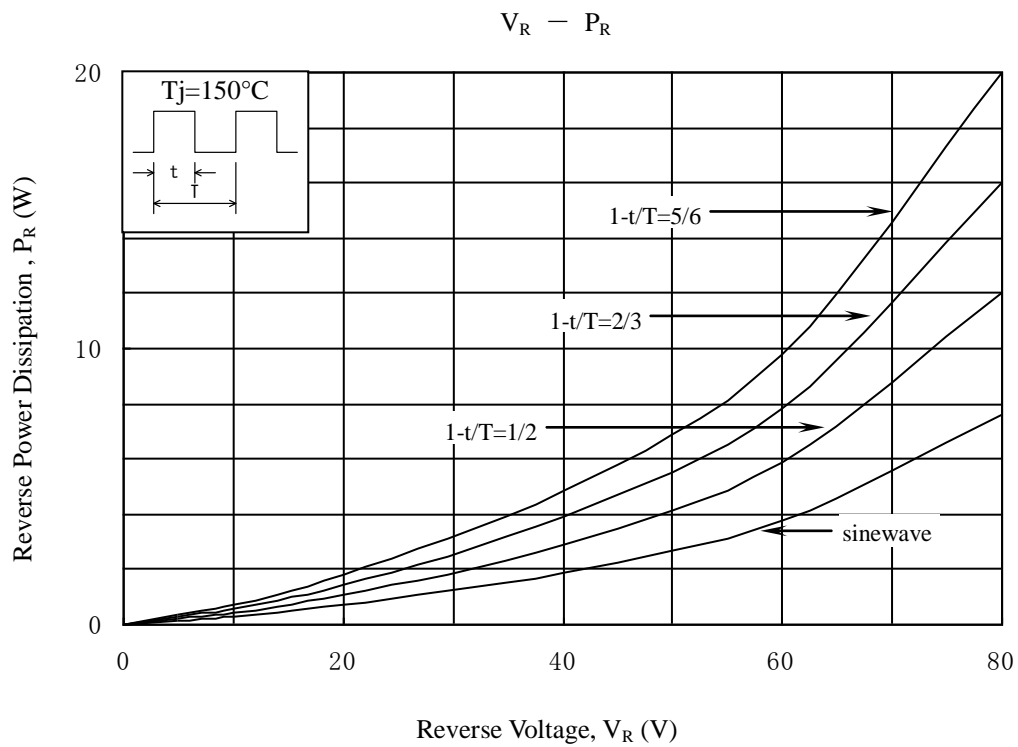
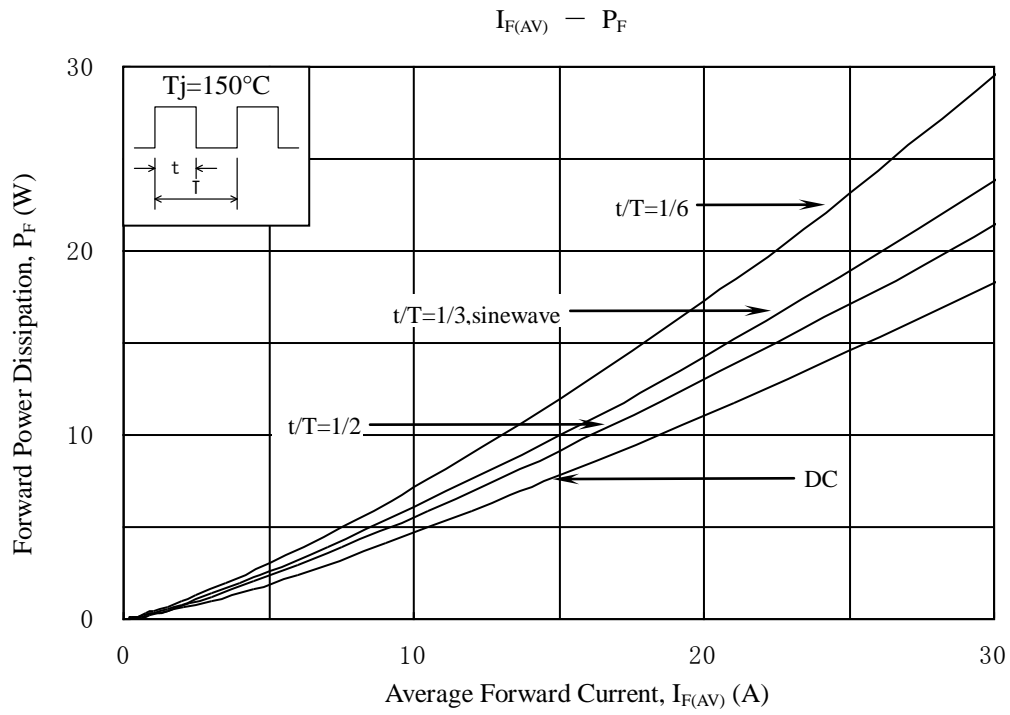


5 Electrical characteristics (Ta=25°C, unless otherwise specified)

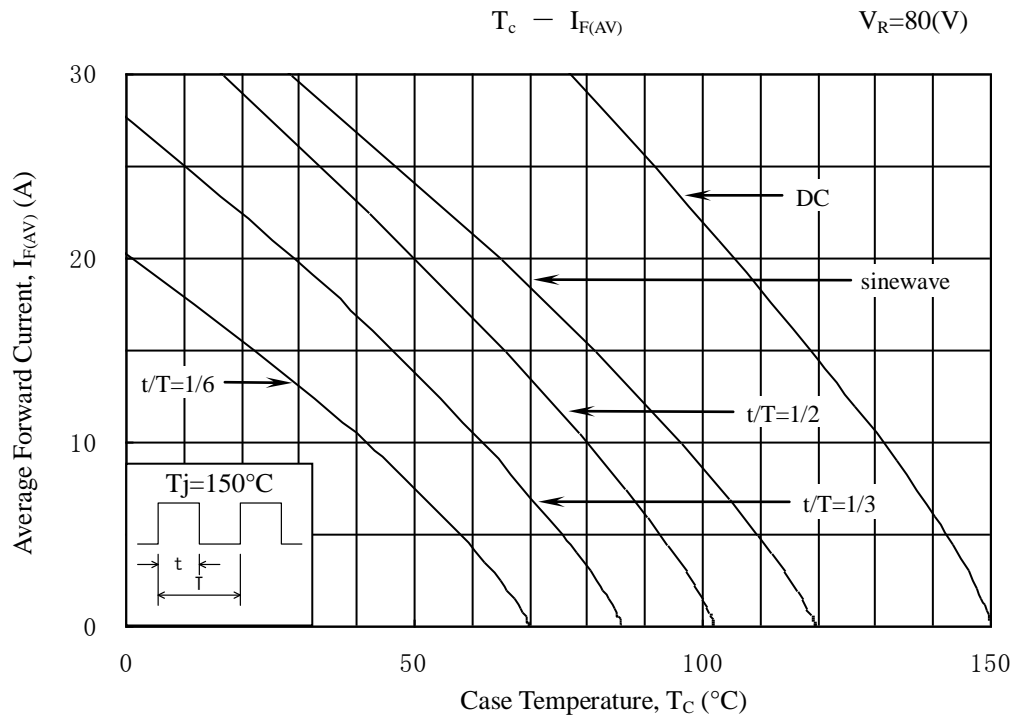
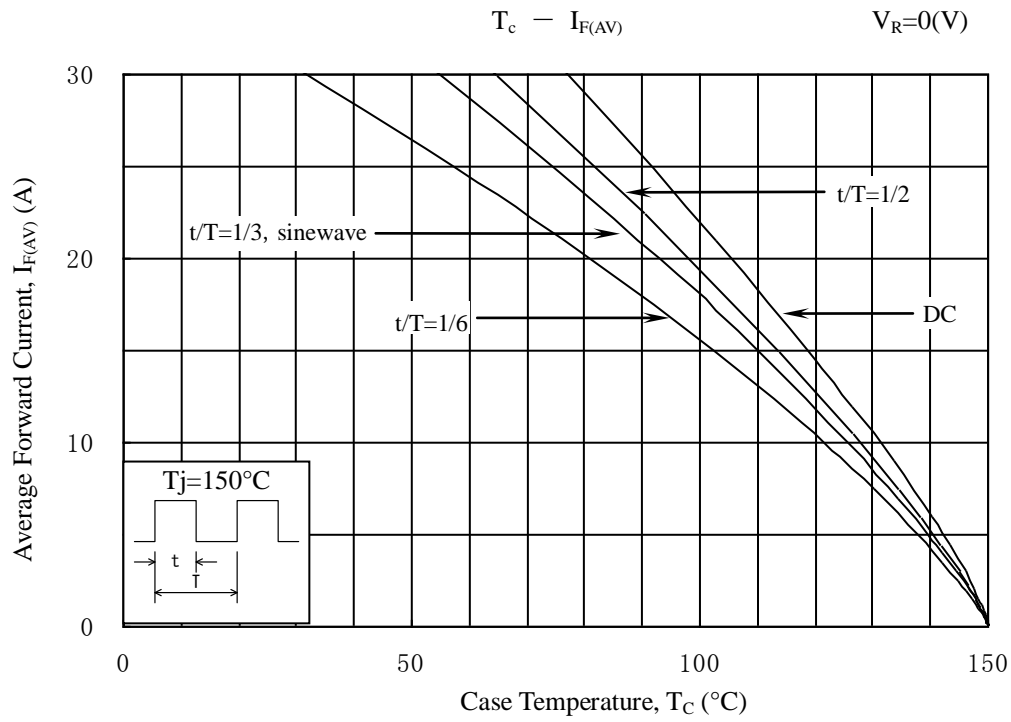
No.	Item	Symbol	Unit	Value	Conditions
1	Forward Voltage Drop	V_F	V	0.765 max.	$I_F=15A$
2	Reverse Leakage Current	I_R	μA	300 max.	$V_R=V_{RM}$
3	Reverse Leakage Current Under High Temperature	$H \cdot I_R$	mA	150 max.	$V_R=V_{RM}$, $T_j=150^{\circ}C$
4	Thermal Resistance	$R_{th(j-c)}$	$^{\circ}C/W$	4.0 max.	Between Junction and case

No.1,2&3 show characteristics per one chip.

6 Characteristics

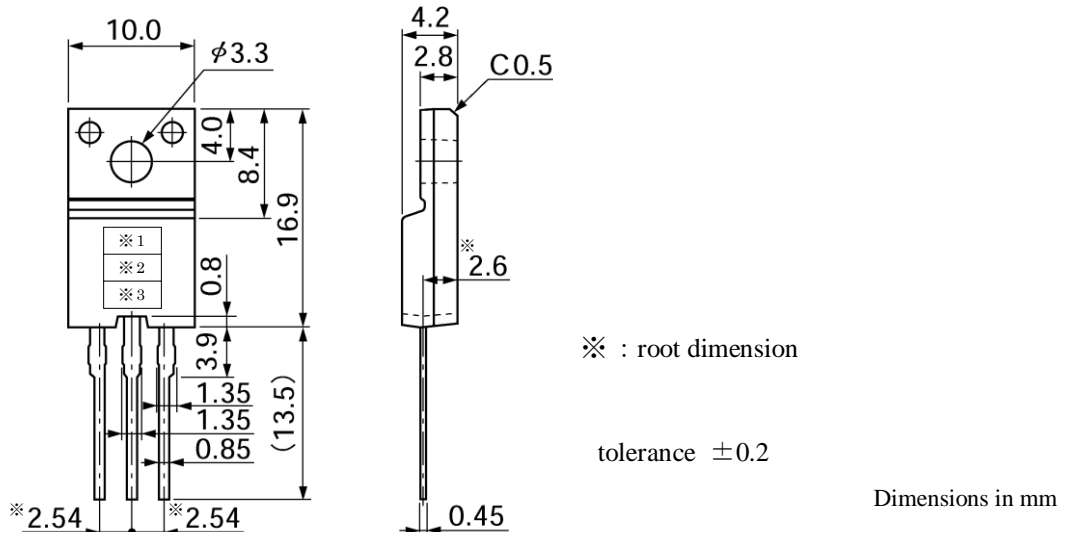


7 Derating



8 Package information

8-1 Package type, physical dimensions and material



8-2 Appearance

The body shall be clean and shall not bear any stain, rust or flaw.

8-3 Marking

Type Name	Marking		
	*1 is type name	*2 is polarity	*3 is lot number
FMEN-2308	EN2308		1st letter: Last digit of year 2nd letter: Month From 1 to 9 for Jan. to Sep., O for Oct., N for Nov., D for Dec. 3rd & 4th letter: Day ex. 2117 (Jan. 17, 2002)